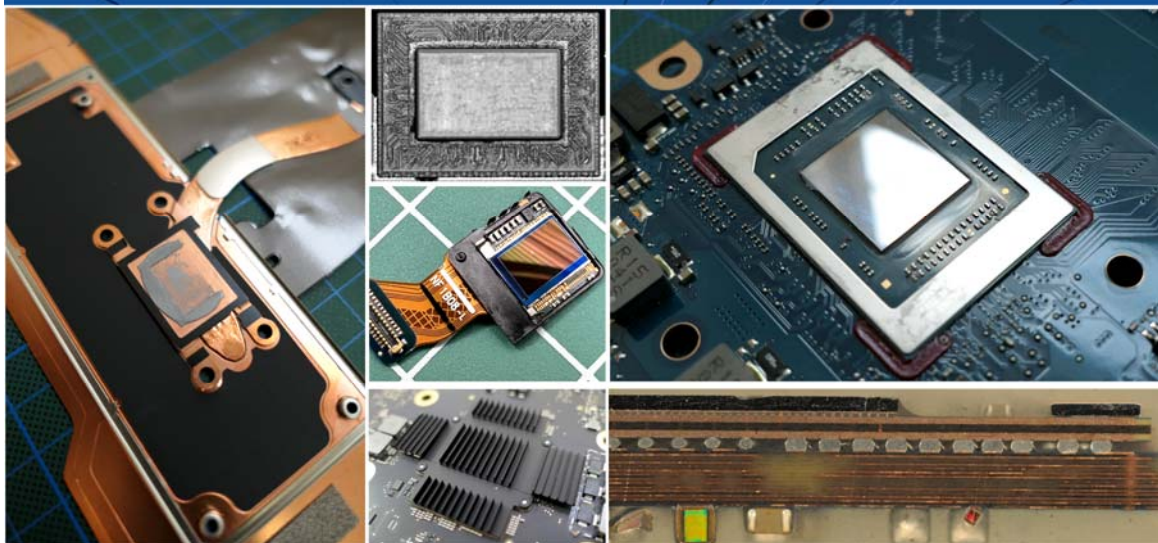


THE SEMICONDUCTOR AND PACKAGING REPORT

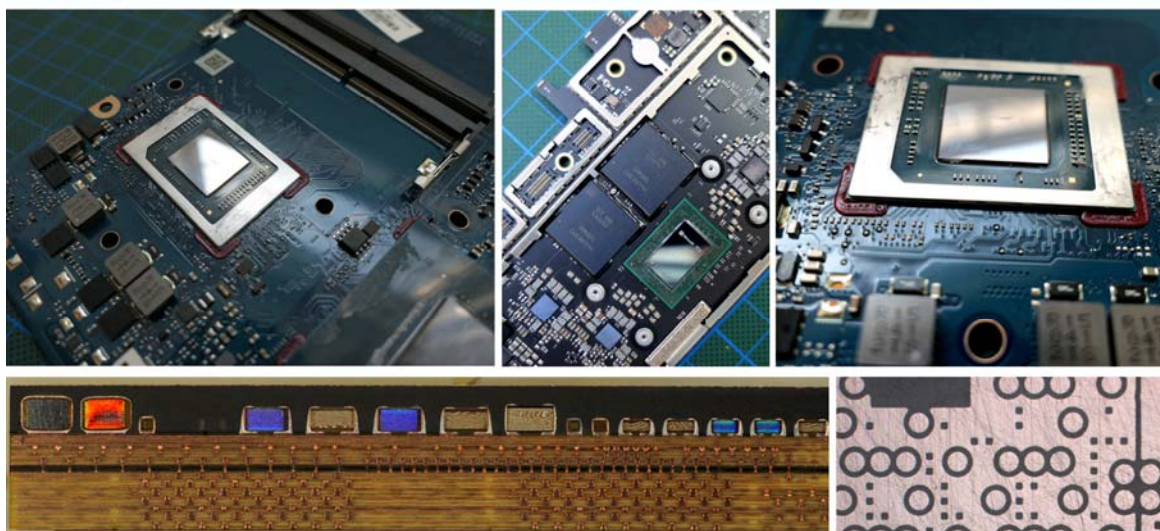
FIRST QUARTER • MAY 2022



- State of the Semiconductor and Package Business
 - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2021 and 2022, including COVID-19 impact and Russia's war in Ukraine; actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: Market Update
 - Review of Semiconductor market and package trends for 2021 and an outlook to 2026
- High Performance Silicon Packaging: Focus On Embedded Bridge And Multichip Packages
 - Review of leading edge silicon packaging technology development with a focus on embedded bridge and multichip packages
- Updates on China's Semiconductor Industry
 - Overview of China's semiconductor industry
- Company News: Semiconductor and Wafer Fabrication
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
 - Recent developments in packaging at leading OSAT and captive assembly operations

THE SEMICONDUCTOR AND PACKAGING REPORT

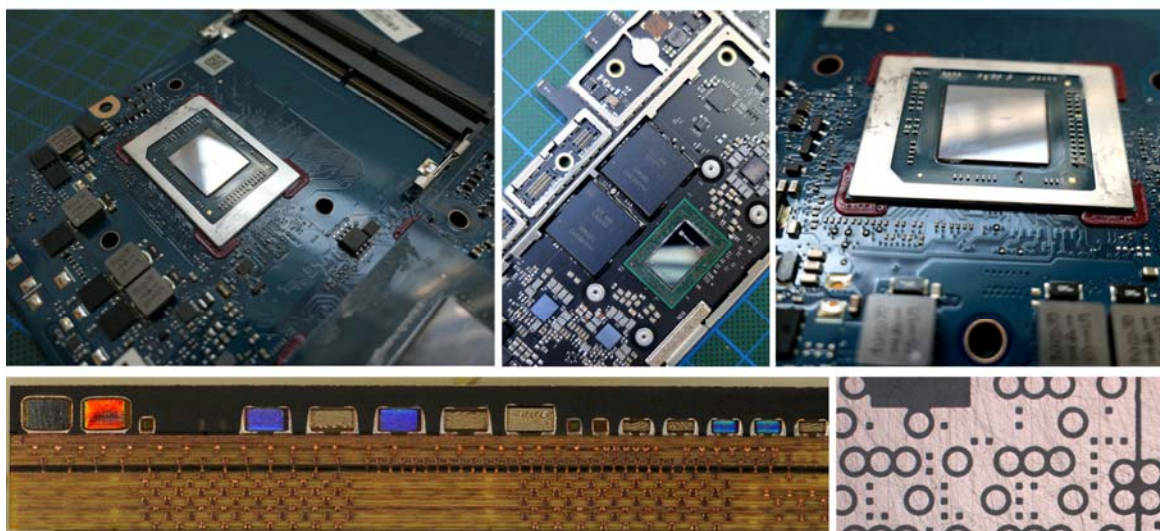
FOURTH QUARTER • APRIL 2022



- State of the Semiconductor and Package Business
 - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2021 and 2022; actual and forecast quarterly sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries. Includes a refresh of the packaging unit and forecast demand for IC components.
- Semiconductor and Packaging: Five-Year Outlook
 - Review of Semiconductor market and package trends for 2021, 2022, and an outlook to 2026.
- Package Substrate Market Developments
 - A review of the current state of the package substrate market segment, highlights some technology trends that are driving the forecast, and discusses concerns about the current level of capex spending in this segment.
- Updates on Taiwanese ODMs (Notebook PCs and Servers)
 - Summary of the Taiwan's leading ODM players for notebook PCs and servers.
- Company News: Semiconductor and Wafer Fabrication
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings.
- Company News: Semiconductor Packaging
 - Recent developments in packaging at leading OSAT and captive assembly operations.

THE SEMICONDUCTOR AND PACKAGING REPORT

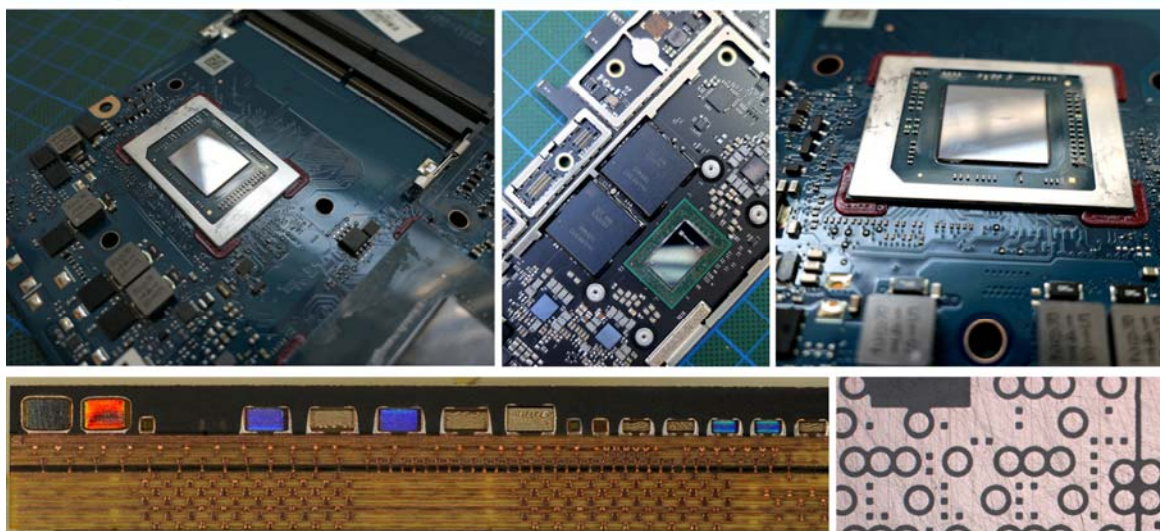
THIRD QUARTER • DECEMBER 2021



- State of the Semiconductor and Package Business
 - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2021 and 2022; actual and forecast quarterly sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries. Includes a refresh of the packaging unit and forecast demand for IC components.
- Semiconductor and Packaging: Revised Outlook
 - Review of semiconductor market and package trends for 2021, 2022, and a revised outlook to 2025.
- System-in-Package (SiP) Market Update and Technology Trends
 - An updated Review of the fast growth SiP market including stacked CSP, PoP, RF modules, AiP, MEMS, Power SiP, and camera modules.
- Updates on China's Wafer Fabrication and Fabless CPU Suppliers
 - Summary of the world's leading ODM players for servers, all of whom are based in Taiwan and China.
- Company News: Semiconductor and Wafer Fabrication
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings.
- Company News: Semiconductor Packaging
 - Recent developments in packaging at leading OSAT and captive assembly operations.

THE SEMICONDUCTOR AND PACKAGING REPORT

SECOND QUARTER • SEPTEMBER 2021



- State of the Semiconductor and Package Business
 - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2021 and 2022; actual and forecast quarterly sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: Revised Outlook
 - Review of semiconductor market and package trends for 2021, 2022, and a revised outlook to 2025.
- Laminate-Based Packages and Package Substrates
 - An updated review of the fast growth package substrate market including wire bond BGA/CSP, FCCSP, FCBGA/LGA, and SiP. Includes trends and investments by leading suppliers to address rapid demand growth and alleviate shortage concerns.
- Updates on Server Market and Players in China and Taiwan
 - Summary of the world's leading ODM players for servers, all of whom are based in Taiwan and China.
- Company News: Semiconductor and Wafer Fabrication
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings.
- Company News: Semiconductor Packaging
 - Recent developments in packaging at leading OSAT and captive assembly operations.



*CONSULTANTS TO THE ELECTRONICS INDUSTRY
BUSINESS OPPORTUNITY FROM TECHNOLOGY AND
MARKET CHANGES*

PRISMARK PARTNERS LLC

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130 Main Street, Cold Spring Harbor, NY 11724 USA • Telephone: 631-367-9187 • Fax: 631-367-9223 • e-mail: partners@prismark.com

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